

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

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TC 2000 MAIL ROOM

Applicant(s): Perez, Erasmo; Roman, David T.

Assignee: Amkor Technology, Inc.

Title: Semiconductor Package With Exposed Die Pad And Body-Locking Leadframe

Serial No.: 09/436,158

Filing Date: November 9, 1999

Examiner: N. Ha

Group Art Unit: 2814

Docket No.: M-7744 US

San Jose, California

August 22, 2001

COMMISSIONER FOR PATENTS
Washington, D. C. 20231

REPLY TO OFFICE ACTION DATED 04/25/01 (37C.F.R.§1.111)

Dear Sir:

The following Amendment and Remarks are in Reply to the April 25, 2001 Office Action in the above-identified Application. In light of this Reply, further examination and consideration of this Application are respectfully requested.

AMENDMENT

Please amend the above-identified Application as follows.

In the Claims:

Please cancel claim 29.

Please amend claim 28 as indicated in "Attachment A" hereto.

The following is a clean version of the entire set of pending claims, including the claims cancelled, amended, and added previously and as above.

Serial No. 09/436,158